

General Description

The MY5N10BF is Power MOSFET , Very low on-resistance ,which provides excellent $R_{DS(ON)}$ and efficiency for most of the small power switching and load switch applications.

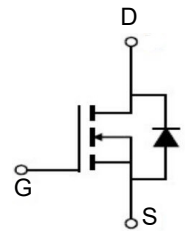
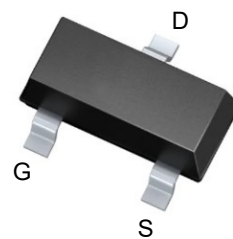


Features

V_{DSS}	100	V
I_D	5	A
$R_{DS(ON)}(at V_{GS}=10V)$	110	m Ω
$R_{DS(ON)}(at V_{GS}=4.5V)$	125	m Ω

Application

- Battery protection
- Load switch
- Power management



Package Marking and Ordering Information

Product ID	Pack	Marking	Qty(PCS)
MY5N10BF	SOT-23	5N10	3000

Absolute Maximum Ratings ($T_A=25^{\circ}\text{C}$ unless otherwise noted)

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	100	V
V_{GS}	Gate-Source Voltage	± 20	V
$I_{D@T_A=25^{\circ}\text{C}}$	Continuous Drain Current, V_{GS} @ 10V ¹	5	A
$I_{D@T_A=70^{\circ}\text{C}}$	Continuous Drain Current, V_{GS} @ 10V ¹	4.6	A
I_{DM}	Pulsed Drain Current ²	20	A
$P_{D@T_A=25^{\circ}\text{C}}$	Total Power Dissipation ³	1.5	W
T_{STG}	Storage Temperature Range	-55 to 150	$^{\circ}\text{C}$
T_J	Operating Junction Temperature Range	-55 to 150	$^{\circ}\text{C}$
$R_{\theta JA}$	Thermal Resistance Junction-ambient(steady state) ¹	135	$^{\circ}\text{C/W}$
	Thermal Resistance Junction-ambient($t < 10s$) ¹	85	$^{\circ}\text{C/W}$

Electrical Characteristics (T_J=25 °C, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _D =250uA	100	---	---	V
ΔBV _{DSS} /ΔT _J	BVDSS Temperature Coefficient	Reference to 25°C, I _D =1mA	---	0.122	---	V/°C
R _{DS(ON)}	Static Drain-Source On-Resistance ²	V _{GS} =10V, I _D =2A	---	110	152	mΩ
		V _{GS} =4.5V, I _D =1A	---	125	158	mΩ
V _{GS(th)}	Gate Threshold Voltage	V _{GS} =V _{DS} , I _D =250uA	1.0	1.5	2.5	V
ΔV _{GS(th)}	V _{GS(th)} Temperature Coefficient		---	-4.84	---	mV/°C
I _{DSS}	Drain-Source Leakage Current	V _{DS} =80V, V _{GS} =0V, T _J =25°C	---	---	10	uA
		V _{DS} =80V, V _{GS} =0V, T _J =55°C	---	---	100	
I _{GSS}	Gate-Source Leakage Current	V _{GS} =±20V, V _{DS} =0V	---	---	±100	nA
g _{fs}	Forward Transconductance	V _{DS} =5V, I _D =2A	---	10.2	---	S
R _g	Gate Resistance	V _{DS} =0V, V _{GS} =0V, f=1MHz	---	2.3	4.6	Ω
Q _g	Total Gate Charge (10V)	V _{DS} =60V, V _{GS} =10V, I _D =2A	---	25.5	---	nC
Q _{gs}	Gate-Source Charge		---	4.2	---	
Q _{gd}	Gate-Drain Charge		---	4.3	---	
T _{d(on)}	Turn-On Delay Time	V _{DD} =50V, V _{GS} =10V, R _G =3.3, I _D =1A	---	17.3	---	ns
T _r	Rise Time		---	2.8	---	
T _{d(off)}	Turn-Off Delay Time		---	50	---	
T _f	Fall Time		---	2.8	---	
C _{iss}	Input Capacitance	V _{DS} =15V, V _{GS} =0V, f=1MHz	---	1077	---	pF
C _{oss}	Output Capacitance		---	46	---	
C _{rss}	Reverse Transfer Capacitance		---	32	---	
I _S	Continuous Source Current ^{1,4}	V _G =V _D =0V, Force Current	---	---	2	A
V _{SD}	Diode Forward Voltage ²	V _{GS} =0V, I _S =1A, T _J =25°C	---	---	1.2	V

Note :

- 1.The data tested by surface mounted on a 1 inch² FR-4 board with 20Z copper.
- 2.The data tested by pulsed, pulse width ≤ 300us, duty cycle ≤ 2%
3. The power dissipation is limited by 150°C junction temperature
4. The data is theoretically the same as I_D and I_{DM}, in real applications, should be limited by total power dissipation.

Typical Electrical and Thermal Characteristics

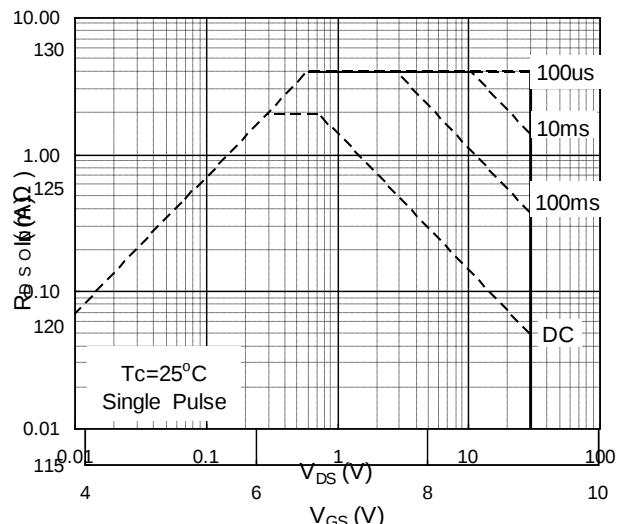
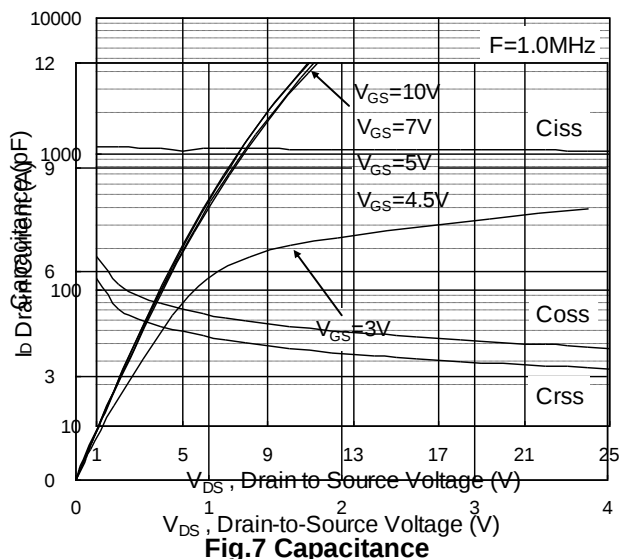


Fig.1 Typical Output Characteristics

Fig.2 On-Resistance vs. Gate-Source

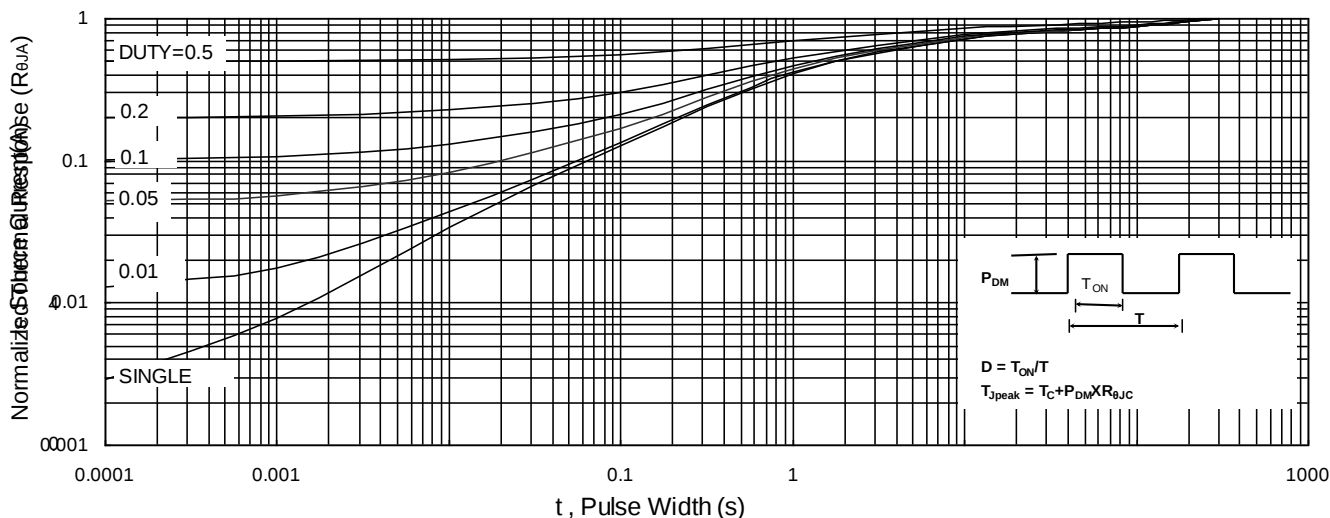
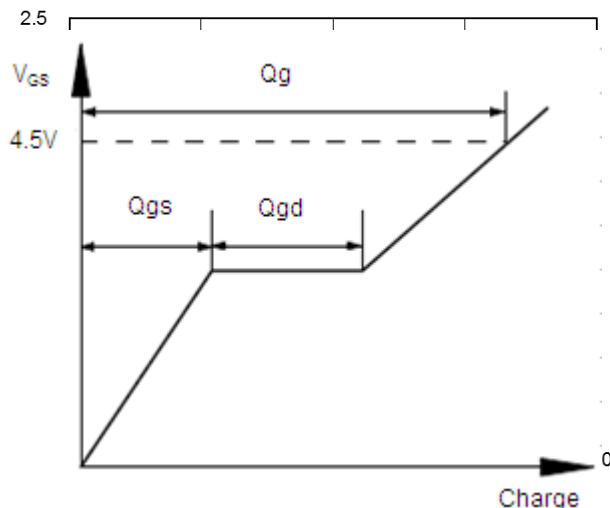
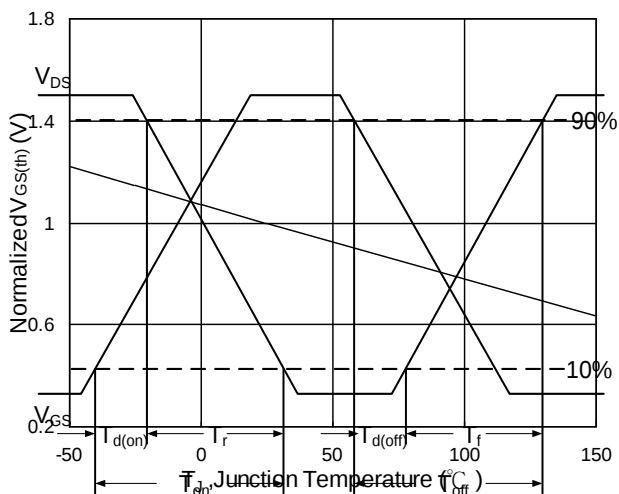


Fig.4 Gate-Charge Characteristics

Fig.9 Normalized Maximum Transient Thermal Impedance



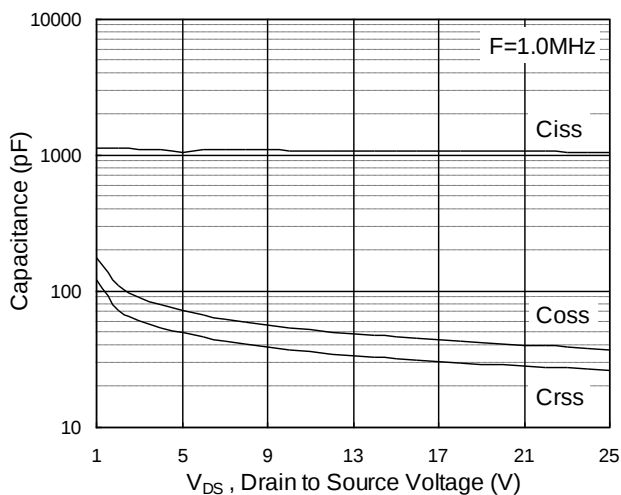


Fig.7 Capacitance

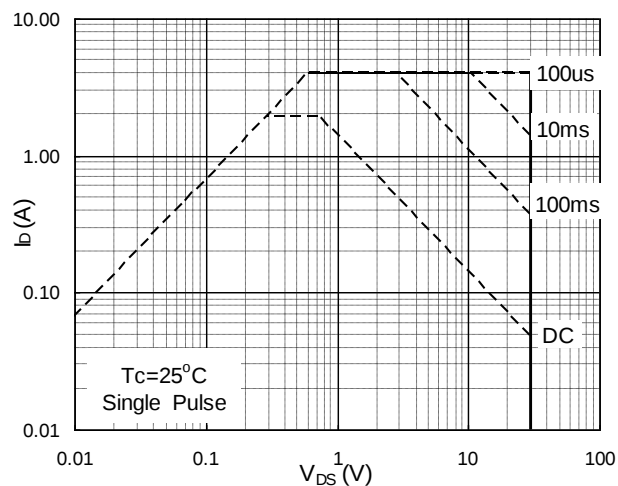


Fig.8 Safe Operating Area

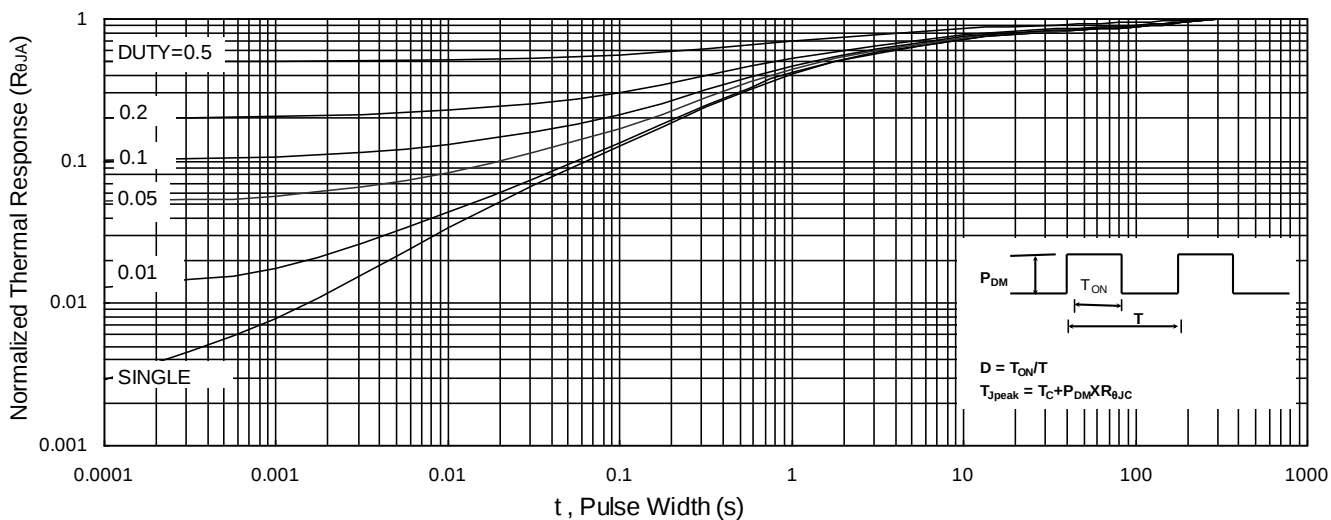


Fig.9 Normalized Maximum Transient Thermal Impedance

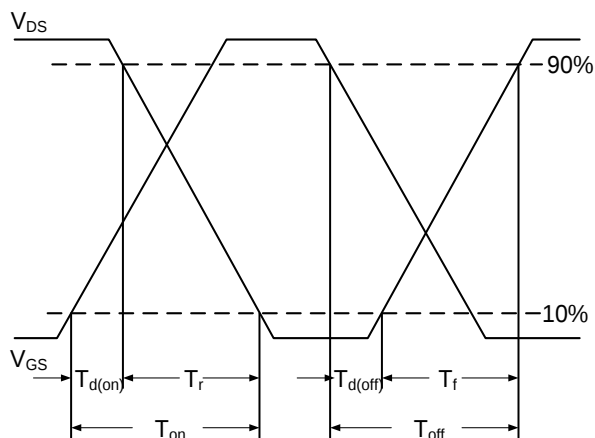


Fig.10 Switching Time Waveform

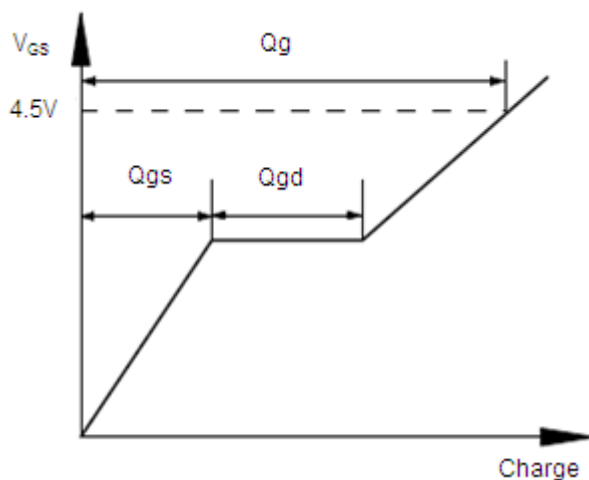
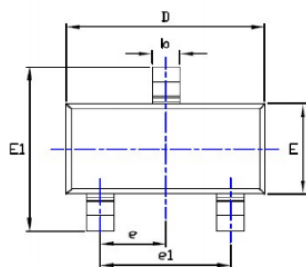
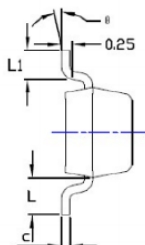


Fig.11 Gate Charge Waveform

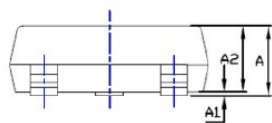
Package Mechanical Data-SOT-23



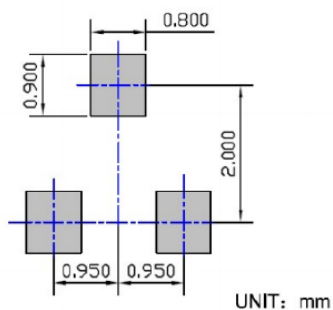
TOP VIEW



SIDE VIEW



SIDE VIEW



SUGGESTED SOLDER PAD LAYOUT

SYMBOL	DIMENSIONS					
	INCHES			Millimeter		
	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.
A	0.035	---	0.045	0.900	---	1.150
A1	0.000	---	0.004	0.000	---	0.100
A2	0.035	0.038	0.041	0.900	0.975	1.050
b	0.012	0.016	0.020	0.300	0.400	0.500
c	0.004	---	0.008	0.100	---	0.200
D	0.110	0.114	0.118	2.800	2.900	3.000
E	0.047	0.051	0.055	1.200	1.300	1.400
E1	0.089	0.094	0.100	2.250	2.400	2.550
e	0.037 TYP			0.950 TYP		
e1	0.071	0.075	0.079	1.800	1.900	2.000
L	0.022 REF			0.550 REF		
L1	0.012	0.016	0.200	0.300	0.400	0.500
ø	0*	---	8*	0*	---	8*

NOTE:

- 1.PACKAGE BODY SIZES EXCLUDE MOLD FLASH AND GATE BURRS.
- 2.TOLERANCE 0.1mm UNLESS OTHERWISE SPECIFIED.
- 3.THE PAD LAYOUT IS FOR REFERENCE PURPOSES ONLY.